



## FACED PANEL

### CEPPO UB55

SUPPORT: Chipboard, MDF  
FORMAT: 5600 x 2070 mm  
THICKNESS: from 8 to 38 mm  
TEXTURE ORIENTATION: Vertical  
BACK TEXTURE: Ceppo  
NOMINAL OVERTHICKNESS: +0.1 mm

## LAMINATE

### CEPPO UB55

TYPE: HPL  
FORMAT: 2760 x 2040 mm  
THICKNESS: 0.9 mm

## EDGE

### CEPPO UB55

TYPE: ABS  
HEIGHT: from 15 to 330 mm  
THICKNESS: from 0.5 to 2.5 mm